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Vishay/Siliconix SIE874DF-T1-GE3

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SiE874DF

RoHS

COMPLIANT

HALOGEN

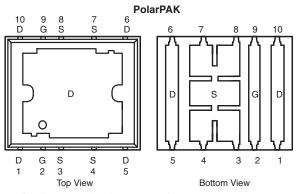
Vishay Siliconix

N-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY						
		I _D (A) ^a				
V _{DS} (V)	R_{DS(on)} (Ω)	Silicon Limit	Package Limit	Q _g (Typ.)		
20	0.00117 at V_{GS} = 10 V	258	60	45 nC		
20	0.0016 at V_{GS} = 4.5 V	220	60	45 110		

Package Drawing

www.vishay.com/doc?72945



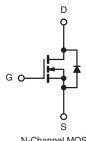
Top surface is connected to pins 1, 5, 6, and 10 Ordering Information: SiE874DF-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- TrenchFET[®] Gen III Power MOSFET
- Ultra Low Thermal Resistance Using Top-Exposed PolarPAK[®] Package for
- Double-Sided Cooling
- Leadframe-Based New Encapsulated Package
 Die Not Exposed
- Same Layout Regardless of Die Size, \leq 100 V
- Low Q_{gd}/Q_{gs} Ratio Helps Prevent Shoot-Through
- 100 % R_a and UIS Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- POL
- OR-ing
- DC/DC



N-Channel MOSFET For Related Documents www.vishay.com/ppg?65350

ABSOLUTE MAXIMUM RATINGS $T_A = 25 \text{ °C}$, unless otherwise noted

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	20	V	
Gate-Source Voltage		V _{GS}	± 20	v	
	T _C = 25 °C		258 (Silicon Limit)		
	1 _C = 25 C		60 ^a (Package Limit)		
Continuous Drain Current (T _J = 150 °C)	T _C = 70 °C	I _D	60 ^a		
	T _A = 25 °C		52 ^{b, c}		
	T _A = 70 °C		42 ^{b, c}	A	
Pulsed Drain Current		I _{DM}	100		
Continuous Source-Drain Diode Current	T _C = 25 °C		60 ^a		
Continuous Source-Diain Diode Current	T _A = 25 °C	I _S	4.3 ^{b, c}		
Single Pulse Avalanche Current		I _{AS}	40		
Avalanche Energy L = 0.1 mH		E _{AS}	80		
	T _C = 25 °C		125		
Maximum Power Dissipation	T _C = 70 °C	P _D	80	w	
Maximum Fower Dissipation	T _A = 25 °C		5.2 ^{b, c}	vv	
	T _A = 70 °C		3.3 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	
Soldering Recommendations (Peak Tempera	ature) ^{d, e}		260		

Notes:

a. Package limit is 60 A.

b. Surface Mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. See Solder Profile (<u>www.vishay.com/doc?73257</u>). The PolarPAK is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

e. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

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THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, b}	bient ^{a, b} $t \le 10 \text{ s}$		20	24		
Maximum Junction-to-Case (Drain Top)	Steady State	R _{thJC} (Drain)	0.8	1	°C/W	
Maximum Junction-to-Case (Source) ^{a, c}	Cloudy Olale	R _{thJC} (Source)	2.2	2.7		

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

b. Maximum under Steady State conditions is 68 °C/W.

c. Measured at source pin (on the side of the package).

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$	20			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		20		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 6.5			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	1.0	1.7	2.2	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 20 V, V_{GS} = 0 V$			1	μΑ	
		$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 ^{\circ}\text{C}$			10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	25			А	
Drain-Source On-State Resistance ^a	P	V _{GS} = 10 V, I _D = 20 A		0.00095	0.00117	Ω	
	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_{D} = 20 \text{ A}$		0.0013	0.0016		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 20 A		110		S	
Dynamic ^b				•			
Input Capacitance	C _{iss}			6200		pF	
Output Capacitance	C _{oss}	V_{DS} = 10 V, V_{GS} = 0 V, f = 1 MHz		1800			
Reverse Transfer Capacitance	C _{rss}			760			
Tatal Cata Charge	Qg	$V_{DS} = 10 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 20 \text{ A}$		95	145	nC	
Total Gate Charge				45	65		
Gate-Source Charge	Q _{gs}	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 20 \text{ A}$		16			
Gate-Drain Charge	Q _{gd}			13			
Gate Resistance	R _g	f = 1 MHz	0.2	1.1	2.2	Ω	
Turn-On Delay Time	t _{d(on)}			45	70		
Rise Time	t _r	V_{DD} = 10 V, R_L = 1 Ω		35	55	. ns	
Turn-Off Delay Time	t _{d(off)}	${ m I}_{ m D}\cong$ 10 A, ${ m V}_{ m GEN}$ = 4.5 V, ${ m R}_{ m g}$ = 1 Ω		60	90		
Fall Time	t _f			30	45		
Turn-On Delay Time	t _{d(on)}			20	30		
Rise Time	t _r	V_{DD} = 10 V, R_L = 1 Ω		10	15		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ 10 A, V_{GEN} = 10 V, R_g = 1 Ω		55	85		
Fall Time	t _f	-		10	15		
Drain-Source Body Diode Characteristic	s			•			
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			60	۸	
Pulse Diode Forward Current ^a	I _{SM}				100	A	
Body Diode Voltage	V _{SD}	I _S = 10 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			60	90	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	L = 10 A dl/dt = 100 A/up T = 05 °C		75	115	nC	
Reverse Recovery Fall Time	t _a	$I_F = 10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^\circ\text{C}$		27			
Reverse Recovery Rise Time	t _b			33		ns	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





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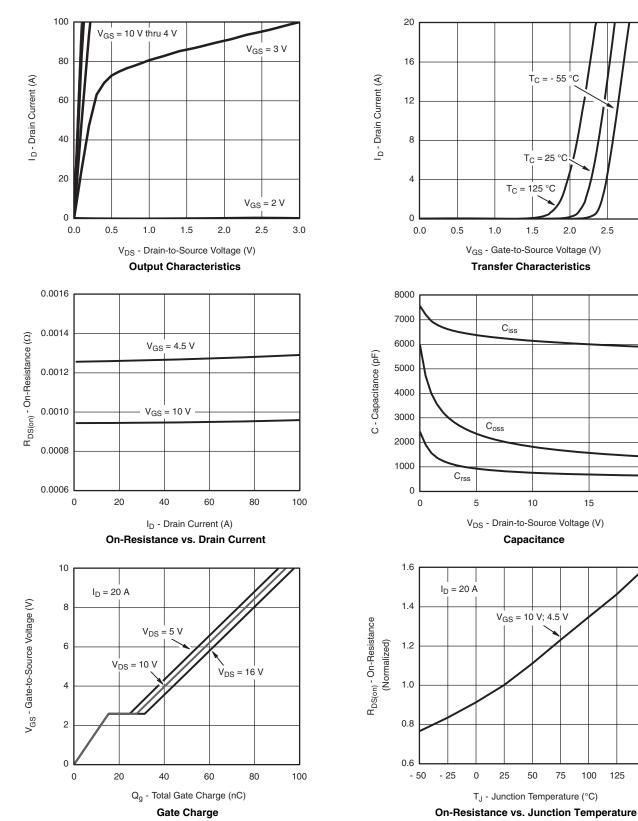
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2.5

15

3.0

20



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

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100

150

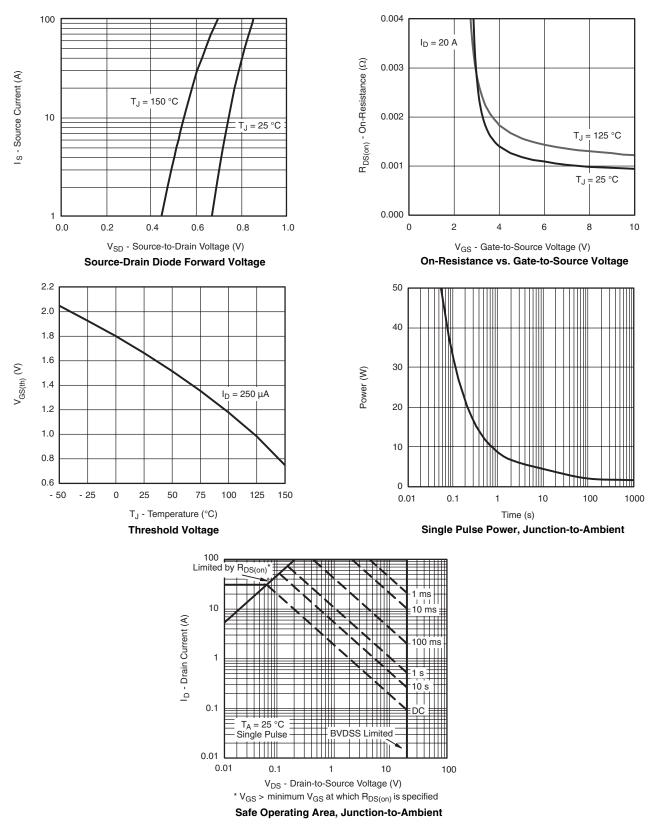


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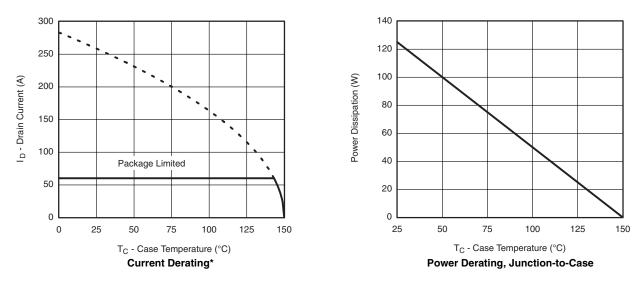
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

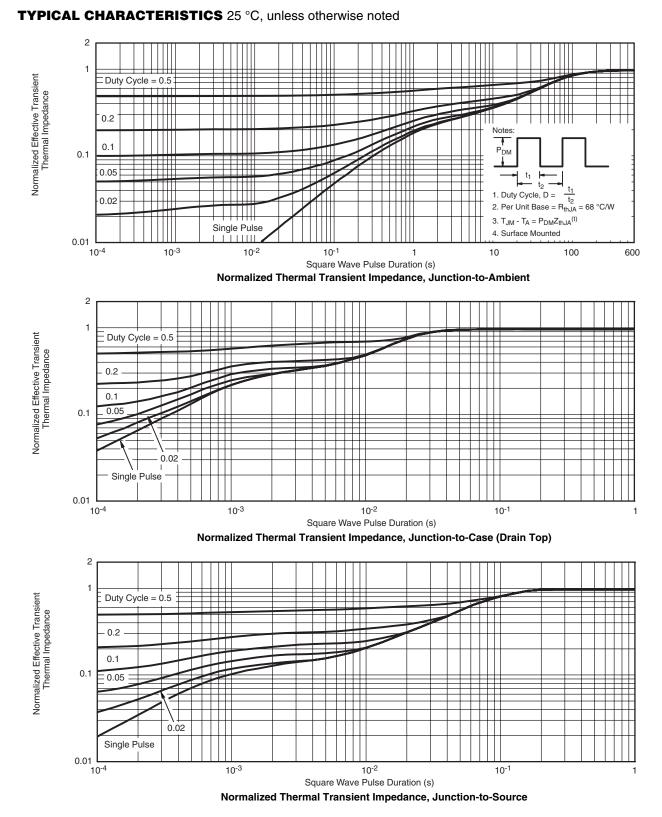
* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



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